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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10030157	FILING DATE 01/30/2002	CLASS 438	SUBCLASS	GAU 2812	EXAMINER GUEP
**APPLICANTS: Robert Philippe;					
OK MC **CONTINUING DATA VERIFIED: THIS APPLICATION IS A 371 OF PCT/FR00/02065 07/18/2000					
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OK MC ** FOREIGN APPLICATIONS VERIFIED: FRANCE 99/09938 07/03/1999					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input checked="" type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input checked="" type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials MC				ATTORNEY DOCKET NO. 218251US6 XPCT	
TITLE : Method for producing via-connections in a substrate and substrate equipped with same					
<small>U.S. DEPT. OF COMM./PAT. & TM-PTO-436L (Rev. 12-94)</small>					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
Assistant Examiner		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg. Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Primary Examiner	
		Prepared for Issue	
		Applicant Examiner	
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